

LAgenaufbau_Contag

Anzahl Cu-Lagen 8

Hydraul. oder ADARA Presse

Ist-Dicke 1,499 mm

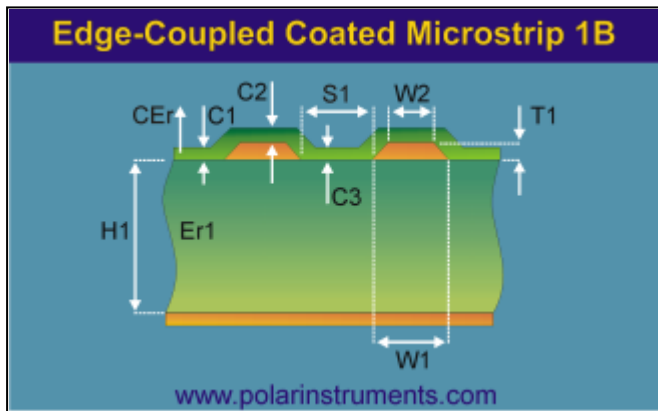
Soll-Dicke 1,500 mm

Soll/Ist-Vergleich 99,91 %

Prepreg-Harzgehalt 65,8 %



Polar Si8000 Controlled Impedance Quick Solver

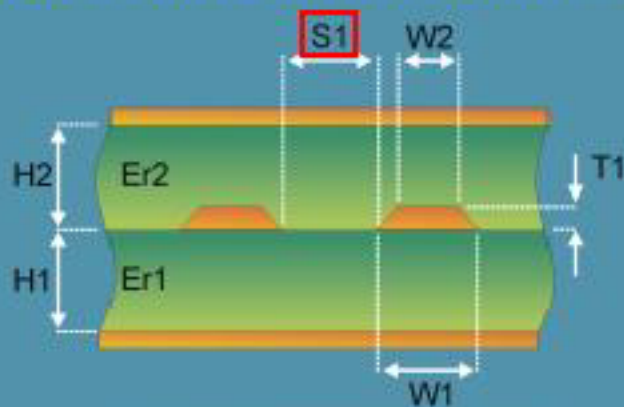


			<u>Toleranz</u>	<u>Minimum</u>	<u>Maximum</u>
Substrat 1 Dicke	H1	130,0000 +/-	0,0000	130,0000	130,0000
Substrat 1 Dielektrikum	Er1	4,1000 +/-	0,0000	4,1000	4,1000
Untere Leiterbreite	W1	132,0000 +/-	0,0000	132,0000	132,0000
Obere Leiterbreite	W2	107,0000 +/-	0,0000	107,0000	107,0000
Leiterbahn Separation	S1	120,0000 +/-	0,0000	120,0000	120,0000
Leiterbahndicke	T1	38,0000 +/-	0,0000	38,0000	38,0000
Lackdicke auf Substrat	C1	20,0000 +/-	0,0000	20,0000	20,0000
Lackdicke auf Leiterbahn	C2	8,0000 +/-	0,0000	8,0000	8,0000
Lackdicke zw. Leiterbahnen	C3	20,0000 +/-	0,0000	20,0000	20,0000
Lack Dielektrikum	CEr	3,6000 +/-	0,0000	3,6000	3,6000
<hr/>					
Differentielle Impedanz	Zdiff	100,51	-----	100,51	100,51
Laufzeit (Odd Mode) (ps/m)	D	5556,610	-----	5556,610	5556,610
Odd Mode Impedanz	Zodd	50,25	-----	50,25	50,25
Even Mode Impedanz	Zeven	76,41	-----	76,41	76,41
Common Mode Impedanz	Zcommon	38,20	-----	38,20	38,20

Hinweise

Leiterbahnbreite 132µm Separation 120µm
Als Bezugsmasse dient die erste Innenlage.

Edge-Coupled Offset Stripline 1B1A



www.polarinstruments.com

Substrat 1 Dicke	H1	250,0000
Substrat 1 Dielektrikum	Er1	4,7000
Substrat 2 Dicke	H2	225,0000
Substrat 2 Dielektrikum	Er2	4,1000
Untere Leiterbreite	W1	100,0000
Obere Leiterbreite	W2	75,0000
Leiterbahn Separation	S1	112,0000
Leiterbahndicke	T1	18,0000
Differentielle Impedanz	Zdiff	100,04

Conductor Impedance

Conductor Width (W)

 mm

Conductor Height (H)

 mm

Frequency (MHz)

Note:

This calculator uses a complex formula, not the simplified formula. Results track the Sonnet 3D solver.

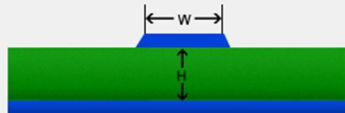
Er Effective = 2.9830

Zo

Lo

Co

Tpd



Options

Base Copper Weight

- ☐ 9um
☒ 18um
☐ 35um
☐ 53um
☐ 70um
☐ 88um
☐ 106um
☐ 142um
☐ 178um

Plating Thickness

- ☐ Bare PCB
☒ 18um
☐ 35um
☐ 53um
☐ 70um
☐ 88um
☐ 106um

Passive Circuits

- ☒ Microstrip
☐ Microstrip Embed
☐ Stripline
☐ Stripline Asym
☐ Dual Stripline
☐ Coplanar Wave

Units

- ☐ Imperial
☒ Metric

Substrate Options

Material Selection

Er

Tg (°C)

Temp Rise (°C)

Temp in (°F) = 36.0

Ambient Temp (°C)

Temp in (°F) = 71.6

Information

Total Copper Thickness
36 umVia Thermal Resistance
179.3 °C/WVia Count:

Conductor Temperature

Temp in (°C) = N/A

Temp in (°F) = N/A

17.9 °C/W per via

Via Voltage Drop

N/A